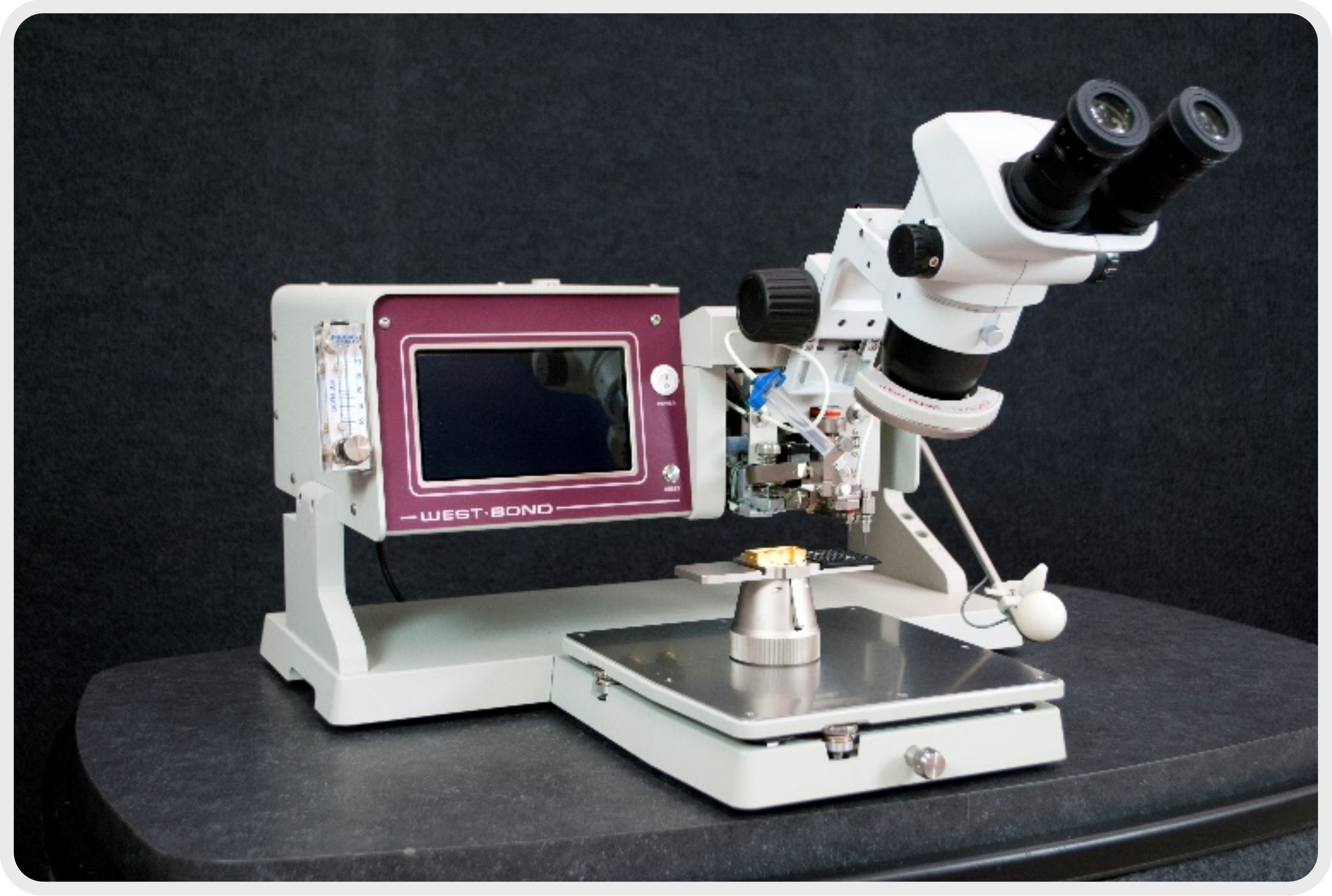
WEST·BOND®



73KF

Convertible
Epoxy Die Bonder
&
Eutectic Die Bonder

UNLIMITED PART SIZE: Access to remote bond targets on large packages, or modules, with WEST·BOND's throat-less chassis and micromanipulator design. This manual model can be configured to bond all types of applications from ● Microwave ● Semiconductor to ● RF and ● Hybrid production.

Lower or Press GO to pick up die

EPOXY 01

Z Elevation 229 mils Buffer 1

CONVERTABILITY:

WEST·BOND introduced the first triple convertible wire bonder back in November of 1969.Today WEST·BOND utilizes the tool head from the E series that can bond it all: Eutectic or Epoxy die attach.

FEATURES:

Programmable force (15-150 grams), primary and secondary ball sizes, pure vertical Z, orthogonal X, Y, Z, 8:1 micromanipulator, pneumatic braking of all axes during bonding and programmable radiant tool heat. The system is available without the base and work platform as a 73KFX for tabletop or conveyor system. Risers are also available for extra tall parts.

MACHINE SPECIFICATIONS:

- Control Logic: Cortex M7 Microcontroller
- Memory: 2MB Solid State RAM
- Data Entry: 7" LCD Capacitive Touch Screen

BOND AREA

- ESD Protection: Conductive and dissipative 10^6
- Bond Platform: 11" x 11" (280 mm x 280 mm)

○ Optional: 20" x 20" (508 mm x 508 mm)

- Z Travel: 14.3 mm / 12µm resolution
- XY Travel: 17.8 mm^2
- Manual control via an 8:1 ratio micromanipulator

TOOL CAPABILITY

Shank Length: 16 mm – Pick up Tool & Die Collet

Tool Diameter: 1/16" (1.58mm)

BOND PARAMETERS

- Bond Force: 15 - 150 grams
- Epoxy Flow Time: On or 1 – 1000 ms.
- Eutectic Scrub Direction L / R / Both
- Eutectic Scrub Stroke 1 – 20 mil (+/-)
- Eutectic Cycle 0 – 100

FACILITY REQUIMENTS

- 100 – 240 VAC 50/60Hz
- 50 PSI clean dry air
- Min. 15inHg vacuum

- **Dimensions:** 24" W x 22.5" D x 12.25" H
- **Weight:** Crated with Accessories 53.5 kg

- Disposable Syringe Setup: 3 or 5cc